Sierra Components, Inc.

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2 1 16 15

DIE ID. →

14

3 13

74 mils

4 12

5 11

6

7 8 9 10

64 mils

NOTE: Chip must be connected to GND

PAD	FUNCTION
1	INPUT A
2	OUTPUT A2
3	OUTPUT A1
4	ENABLE
5	OUTPUT B1
6	OUTPUT B2
7	INPUT B
8	GND
9	INPUT C
10	OUTPUT C2
11	OUTPUT C1
12	N. ENABLE
13	OUTPUT D1
14	OUTPUT D2
15	INPUT D
16	VCC

The information given is believed to be correct at the time of issue.
Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

APPROVED		DIE INFORMATION
D Markham .... DATE: 15/8/00	DS26C31C NATIONAL SEMICONDUCTOR	DIMENSIONS (Mils): 64 x 74 x 15 BOND PADS (Mils): 4 x 4 MASK. REF: GEOMETRY: BACK POTENTIAL: GND
SERIAL NUMBER. 004245		METALLISATION TOP: Al BACK: Si